

## SN74HC4851 具有注入电流效应控制功能的 8 通道模拟多路复用器/多路解复用器

### 1 特性

- 注入电流交叉耦合  $<1\text{mV}/\text{mA}$   
( 请参阅应用信息中的节 8.1 )
- 低开关间串扰
- 端子与 SN74HC4051、SN74LV4051A 和 CD4051B 器件兼容
- 2V 至 5.5V  $V_{CC}$  运行
- 闩锁性能超过 100mA，符合 JESD 78 II 类规范的要求

### 2 应用

- 模拟和数字多路复用和多路信号分离
- 诊断和监控
- 数据中心交换机
- 远程无线电单元 (RRU)
- 机架式服务器
- 电表
- 电器
- 空调机
- 多功能打印机
- 串式逆变器
- IP 网络摄像头
- 点钞机
- 非公路用车控制系统
- 数字音频广播

### 3 说明

这款八通道 CMOS 模拟多路复用器/多路解复用器的端子与 '4051 器件的功能兼容，并具有注入电流效应控制功能，此控制功能在电压通常超过正常电源电压的汽车应用中具有出色的价值。

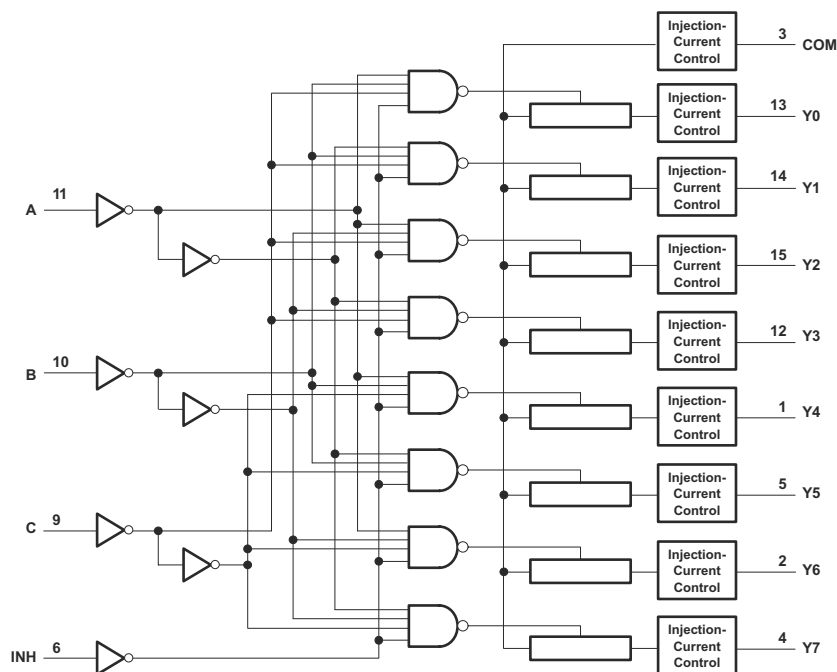
注入电流效应控制功能允许已禁用的模拟输入通道上的信号超过电源电压，而不会影响已启用的模拟通道的信号。由于具备这一特性，不再需要通常使用的外部二极管/电阻器网络将模拟通道信号保持在电源电压范围内。

#### 封装信息

器件型号	封装 <sup>(1)</sup>	封装尺寸 <sup>(2)</sup>
SN74HC4851	PW ( TSSOP , 16 )	5mm × 6.4mm

(1) 有关更多信息，请参阅节 11

(2) 封装尺寸 ( 长 × 宽 ) 为标称值，并包括引脚 ( 如适用 )。



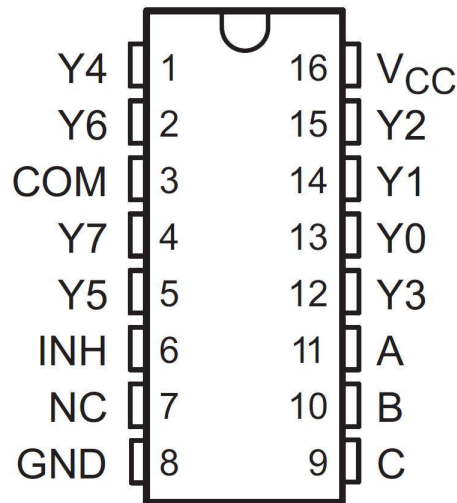
逻辑图 ( 正逻辑 )



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## 4 Pin Configuration and Functions



NC – No internal connection

图 4-1. SN74HC4851 PW Package, 16-Pin TSSOP (Top View)

表 4-1. Function Table

Inputs				On Channel
INH	C	B	A	Yx
L	L	L	L	Y0
L	L	L	H	Y1
L	L	H	L	Y2
L	L	H	H	Y3
L	H	L	L	Y4
L	H	L	H	Y5
L	H	H	L	Y6
L	H	H	H	Y7
H	X	X	X	None

## 5 Specifications

### 5.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)<sup>(1) (2)</sup>

		MIN	MAX	UNIT
V <sub>CC</sub>	Supply voltage	- 0.5	6	V
V <sub>SEL</sub> or V <sub>EN</sub>	Logic control input pin voltage (EN, A0, A1, A2)	- 0.5	V <sub>CC</sub> +0.5V	V
V <sub>S</sub> or V <sub>D</sub>	Source or drain voltage (Sx, D)	- 0.5	V <sub>CC</sub> +0.5V	V
I <sub>IK</sub>	Input clamp current (V <sub>I</sub> < 0 or V <sub>I</sub> > V <sub>CC</sub> )	- 20	20	mA
I <sub>IOK</sub>	I/O diode current (V <sub>IO</sub> < 0 or V <sub>IO</sub> > V <sub>CC</sub> )	- 20	20	mA
I <sub>T</sub>	Switch through current (V <sub>IO</sub> = 0 to V <sub>CC</sub> )	- 25	25	mA
I <sub>GND</sub>	Continuous current through V <sub>CC</sub> or GND	- 50	50	mA
T <sub>stg</sub>	Storage temperature	- 65	150	°C
T <sub>J</sub>	Junction temperature		150	

- (1) Operation outside the *Absolute Maximum Ratings* may cause permanent device damage. Absolute maximum ratings do not imply functional operation of the device at these or any other conditions beyond those listed under *Recommended Operating Conditions*. If briefly operating outside the *Recommended Operating Conditions* but within the *Absolute Maximum Ratings*, the device may not sustain damage, but it may not be fully functional. Operating the device in this manner may affect device reliability, functionality, performance, and shorten the device lifetime.
- (2) The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

### 5.2 ESD Ratings

			VALUE	UNIT
V <sub>(ESD)</sub>	Electrostatic discharge	Human body model (HBM), per AEC Q100-002 <sup>(1)</sup>	±2000	V
		Charged device model (CDM), per AEC Q100-011	±750	

- (1) AEC Q100-002 indicates that HBM stressing shall be in accordance with the ANSI/ESDA/JEDEC JS-001 specification.

### 5.3 Thermal Information: SN74HC485x

THERMAL METRIC <sup>(1)</sup>		SN74HC485x	UNIT
		PW (TSSOP)	
		PINS	
R <sub>θJA</sub>	Junction-to-ambient thermal resistance	139.6	°C/W

- (1) For more information about traditional and new thermal metrics, see the [Semiconductor and IC Package Thermal Metrics](#) application report.

## 5.4 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)

			MIN	NOM	MAX	UNIT
V <sub>CC</sub>	Supply voltage		2		5.5	V
V <sub>IH</sub>	Input logic high	2V	1.5			V
		2.5V	2.1			
		3.3V	2.3			
		4.5V	3.15			
		5.5V	4.2			
V <sub>IL</sub>	Input logic low	2V	0		0.5	V
		2.5V	0		0.7	
		3.3V	0		0.8	
		4.5V	0		0.95	
		5.5V	0		1.05	
V <sub>SEL</sub> or V <sub>EN</sub>	Logic control input pin voltage ( $\overline{EN}$ , A0, A1, A2)		0		V <sub>CC</sub>	V
V <sub>S</sub> or V <sub>D</sub>	Signal path input/output voltage (source or drain pin) (Sx, D)		0		V <sub>CC</sub>	V
$\Delta t / \Delta v$	Input transition rise or fall time	V <sub>CC</sub> = 2V			1000	ns
		V <sub>CC</sub> = 3V			800	
		V <sub>CC</sub> = 3.3V			700	
		V <sub>CC</sub> = 4.5V			500	
		V <sub>CC</sub> = 5.5V			400	
T <sub>A</sub>	Ambient temperature		- 40		125	°C

## 5.5 Electrical Characteristics

 At specified  $V_{CC} \pm 10\%$ 

 Typical values measured at nominal  $V_{CC}$ .

PARAMETER		TEST CONDITIONS	$V_{CC}$	Operating free-air temperature ( $T_A$ )									UNIT
				25°C			- 40°C to 85°C			- 40°C to 125°C			
				MIN	TYP	MAX	MIN	TYP	MAX	MIN	TYP	MAX	
$R_{ON}$	On-state switch resistance	$V_S = 0V$ to $V_{CC}$ $I_{SD} = 0.5mA$	2V	500	650		670		700		$\Omega$		
			3V	215	280		320		360				
			3.3V	210	270		305		345				
			4.5V	160	210		240		270				
$\Delta R_{ON}$	On-state switch resistance matching between inputs	$V_S = V_{CC} / 2$ $I_{SD} = 0.5mA$	2V	4	10		15		20		$\Omega$		
			3V	2	8		12		16				
			3.3V	2	8		12		16				
			4.5V	2	8		12		16				
$I_I$	Control input current	$V_I = V_{CC}$ or GND	5V		$\pm 0.1$		$\pm 0.1$		$\pm 1$	$\mu A$			
$I_{S(OFF)}$	Off-state switch leakage current (any one channel)	Switch Off $V_{INH} = V_{IH}$ $V_D = V_{CC} / GND$ $V_S = GND / V_{CC}$	5V		$\pm 0.1$		$\pm 0.5$		$\pm 1$	$\mu A$			
	Off-state switch leakage current (common channel)				$\pm 0.2$		$\pm 2$		$\pm 4$	$\mu A$			
$I_{S(ON)}$	Channel on-state leakage current	Switch Off $V_{INH} = V_{IL}$ $V_D = V_{CC} / GND$ $V_S = GND / V_{CC}$	5V		$\pm 0.1$		$\pm 0.5$		$\pm 1$	$\mu A$			
$I_{DD}$	$V_{CC}$ supply current	Logic inputs = 0V or $V_{CC}$	5V		2		20		40	$\mu A$			
$C_{IC}$	Control input capacitance	A, B, C, INH		3.5	10		10		10	pF			
$C_{IS}$	Common terminal capacitance	Switch off		22	40		40		40	pF			
$C_{OS}$	Switch terminal capacitance	Switch off		6.7	15		15		15	pF			
$C_{PD}$	Power Dissipation Capacitance	No Load $t_r = t_f = 1ns$ $f = 1MHz$	3.3V	32						pF			
			5V	37									

## 5.6 Timing Characteristics

At specified  $V_{CC} \pm 10\%$

Typical values measured at nominal  $V_{CC}$ .

PARAMETER	TEST CONDITIONS	$V_{CC}$	Operating free-air temperature ( $T_A$ )									UNIT
			25°C			- 40°C to 85°C			- 40°C to 125°C			
			MIN	TYP	MAX	MIN	TYP	MAX	MIN	TYP	MAX	
SWITCHING CHARACTERISTICS <sup>(1)</sup>												
$t_{PD}$	Propagation delay	$C_L = 50\text{pF}$ Sx to D, D to Sx	2V	19.5	25		29		32		ns	
			3V	12	15.5		17.5		19.5			
			3.3V	11	14.5		16.5		18.5			
			5V	8.6	11.5		12.5		13.5			
$t_{TRAN}$	Transition-time between inputs	$R_L = 10\text{k}\Omega$ , $C_L = 50\text{pF}$ Ax to D, Ax to Sx	2V	44	94		103		103		ns	
			3V	30	63		67		67			
			3.3V	23	51		54		54			
			5V	18	43		46		46			
$t_{ON(EN)}$	Turnon-time from enable	$R_L = 10\text{k}\Omega$ , $C_L = 50\text{pF}$ EN to D, EN to Sx	2V		95		105		115		ns	
			3V		90		100		110			
			3.3V		85		95		105			
			5V		80		90		100			
$t_{OFF(EN)}$	Turnoff time from enable	$R_L = 10\text{k}\Omega$ , $C_L = 50\text{pF}$ EN to D, EN to Sx	2V		95		105		115		ns	
			3V		90		100		110			
			3.3V		85		95		105			
			5V		80		90		100			

(1)  $t_{PLH}/t_{PHL} = t_{PD}$  propagation delay time,  $t_{PZH}/t_{PZL} = t_{ON(EN)}$  enable delay time,  $t_{PHZ}/t_{PLZ} = t_{OFF(EN)}$  disable delay time,  $t_{PLH}/t_{PHL}$  Channel select =  $t_{TRAN}$

## 5.7 Injection Current Coupling

At specified  $V_{CC} \pm 10\%$

Typical values measured at nominal  $V_{CC}$  and  $T_A = 25^\circ\text{C}$ .

PARAMETER	$V_{CC}$	TEST CONDITIONS	-40°C to 125°C			UNIT		
			MIN	TYP	MAX			
INJECTION CURRENT COUPLING								
$\Delta V_{OUT}$	Maximum shift of output voltage of enabled analog input <sup>(1)</sup>	3.3V	$R_S \leq 3.9\text{k}\Omega$	$I_{INJ} \leq 1\text{mA}$	0.05	1	mV	
		5V			0.1	1		
		3.3V		$R_S \leq 20\text{k}\Omega$	$I_{INJ} \leq 10\text{mA}$	0.345		5
		5V				0.067		5
		3.3V	$R_S \leq 20\text{k}\Omega$	$I_{INJ} \leq 1\text{mA}$	0.05	2		
		5V			0.11	2		
		3.3V		$I_{INJ} \leq 10\text{mA}$	0.05	20		
		5V			0.024	20		

(1)  $I_{INJ}$  = total current injected into all disabled channels

## 6 Parameter Measurement Information

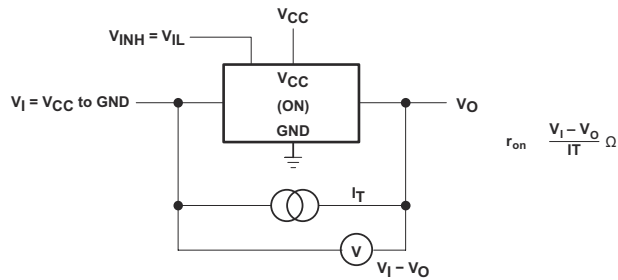


图 6-1. On-State-Resistance Test Circuit

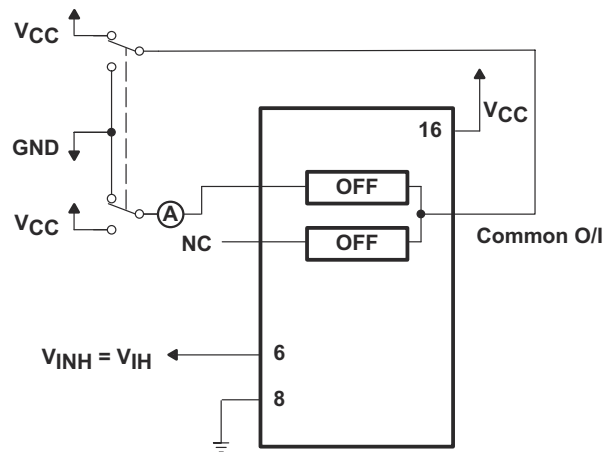


图 6-2. Maximum Off-Channel Leakage Current, Any One Channel, Test Setup

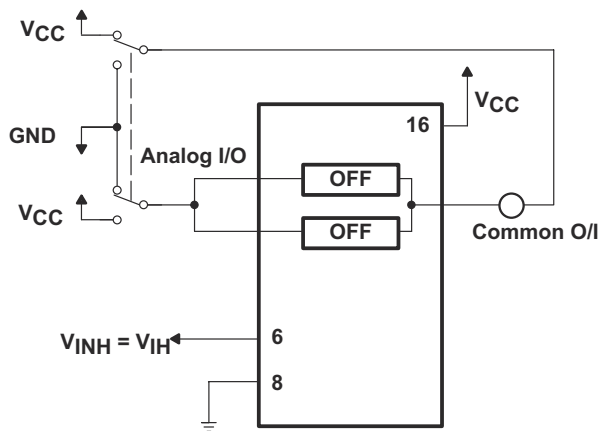


图 6-3. Maximum Off-Channel Leakage Current, Common Channel, Test Setup

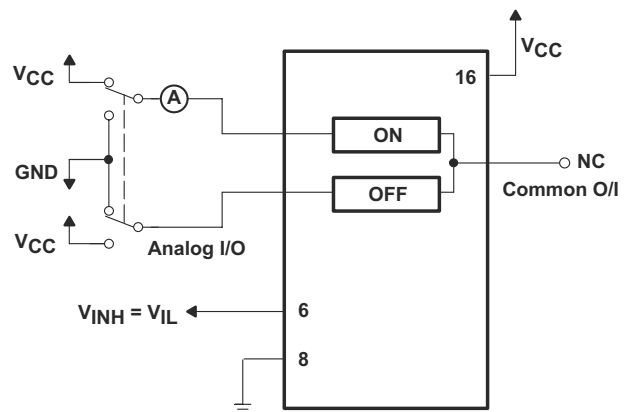


图 6-4. Maximum On-Channel Leakage Current, Channel To Channel, Test Setup

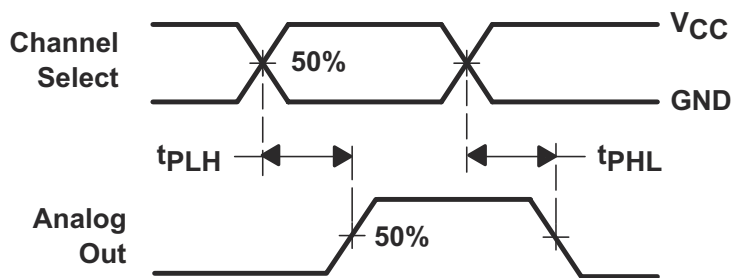
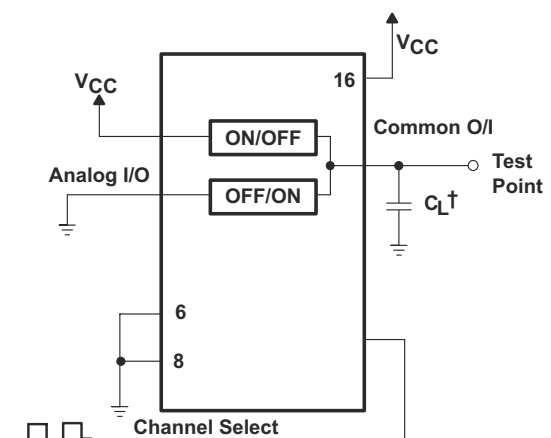


图 6-5. Propagation Delays, Channel Select to Analog Out



† Includes all probe and jig capacitance

图 6-6. Propagation-Delay Test Setup, Channel Select to Analog Out

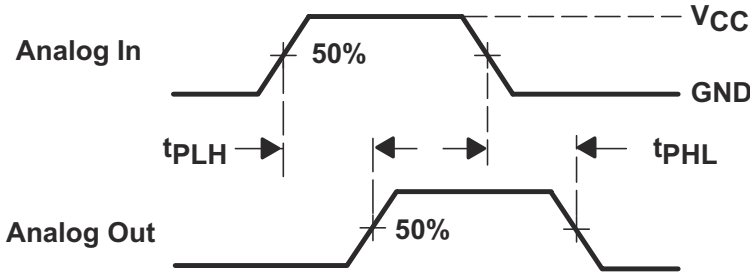
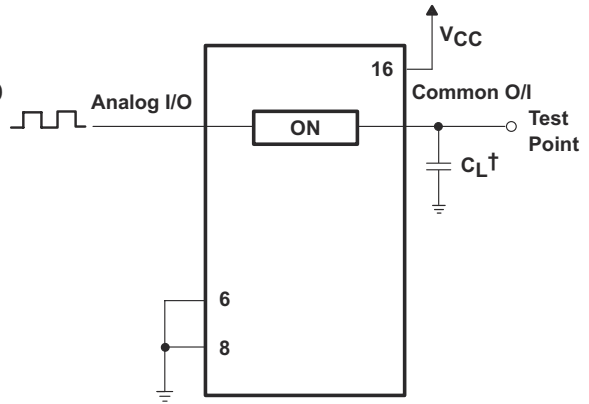


图 6-7. Propagation Delays, Analog In to Analog Out



† Includes all probe and jig capacitance

图 6-8. Propagation-Delay Test Setup, Analog In to Analog Out

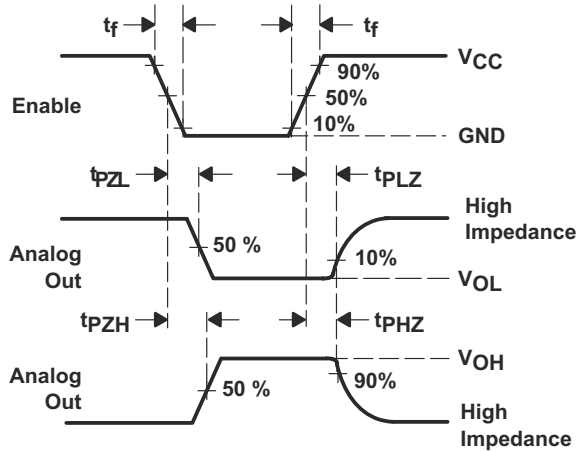


图 6-9. Propagation Delays, Enable to Analog Out

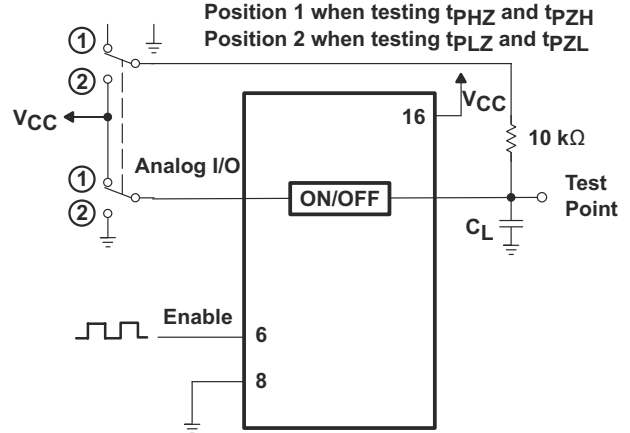


图 6-10. Propagation-Delay Test Setup, Enable to Analog Out

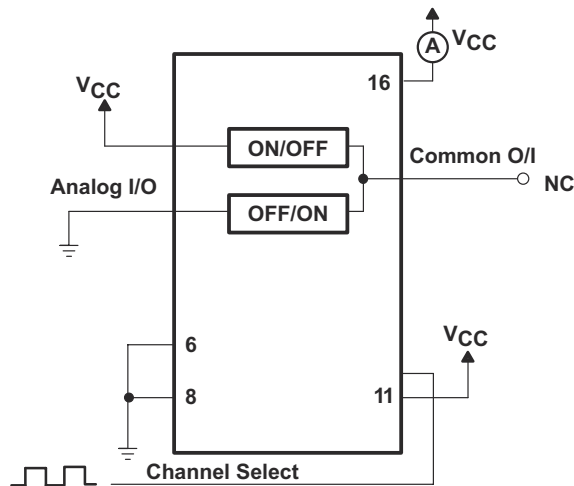


图 6-11. Power-Dissipation Capacitance Test Setup



## 7 Detailed Description

### 7.1 Functional Block Diagram

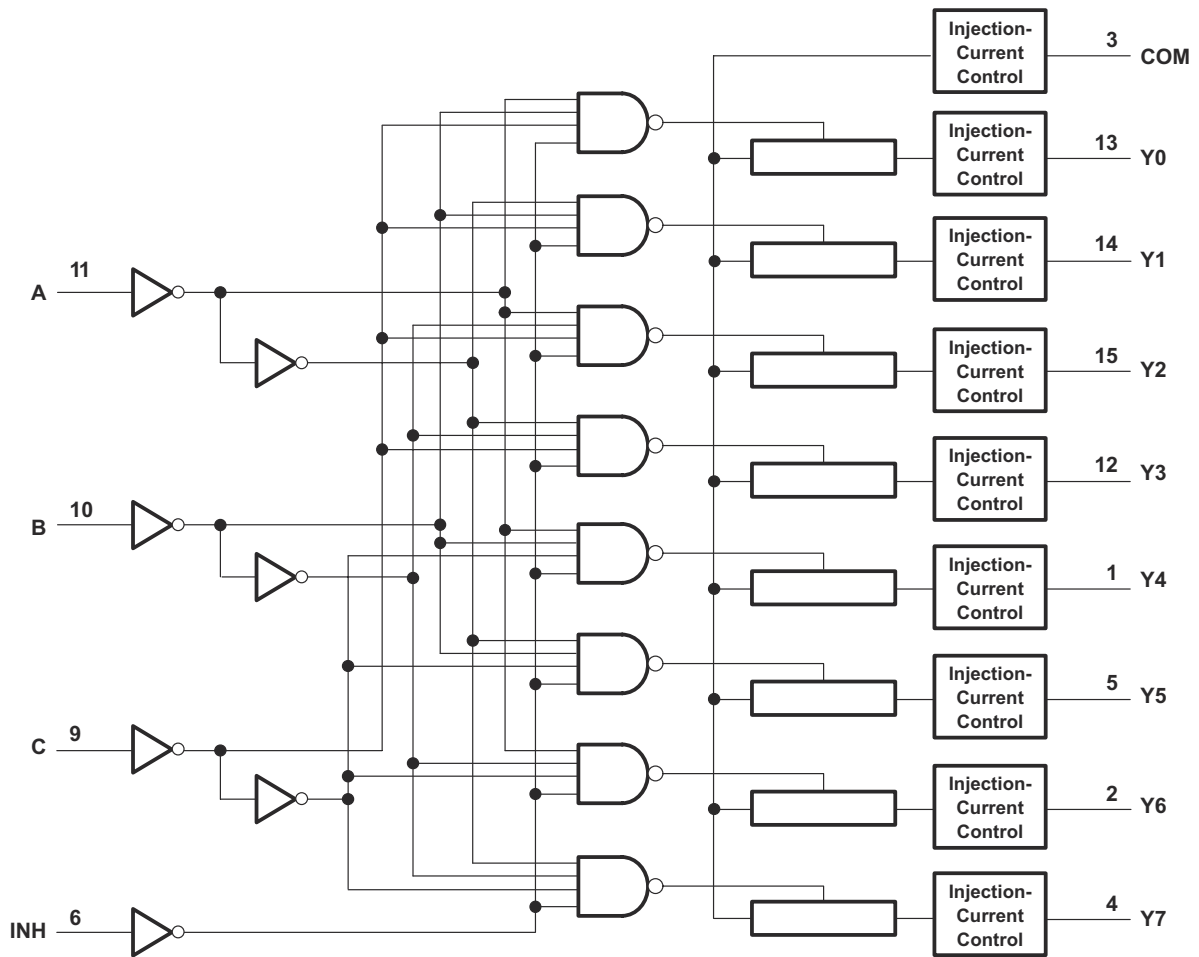


图 7-1. Logic Diagram (Positive Logic)

## 8 Application and Implementation

### 备注

以下应用部分中的信息不属于 TI 元件规格，TI 不担保其准确性和完整性。TI 的客户负责确定元件是否适合其用途，以及验证和测试其设计实现以确认系统功能。

### 8.1 Application Information

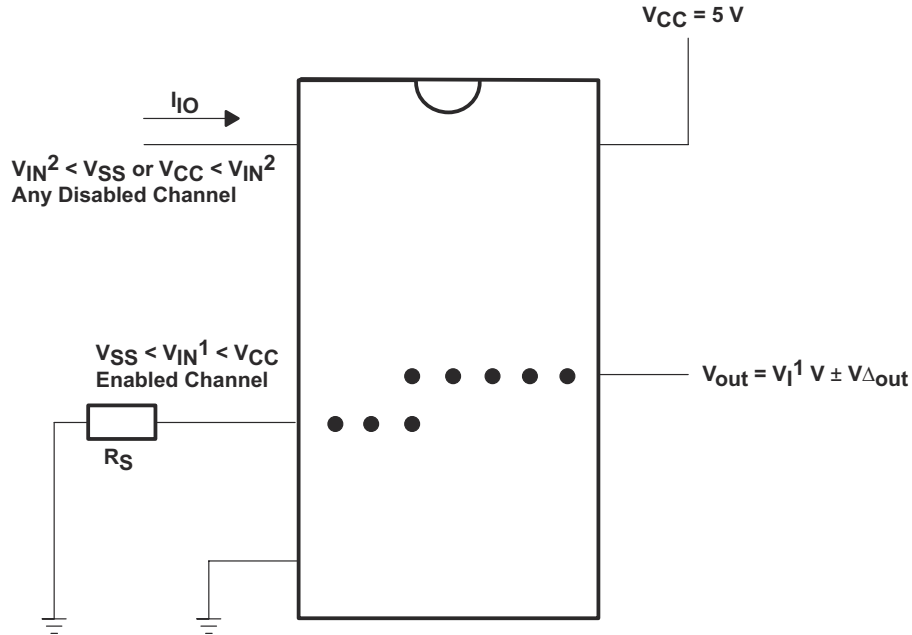


图 8-1. Injection-Current Coupling Specification

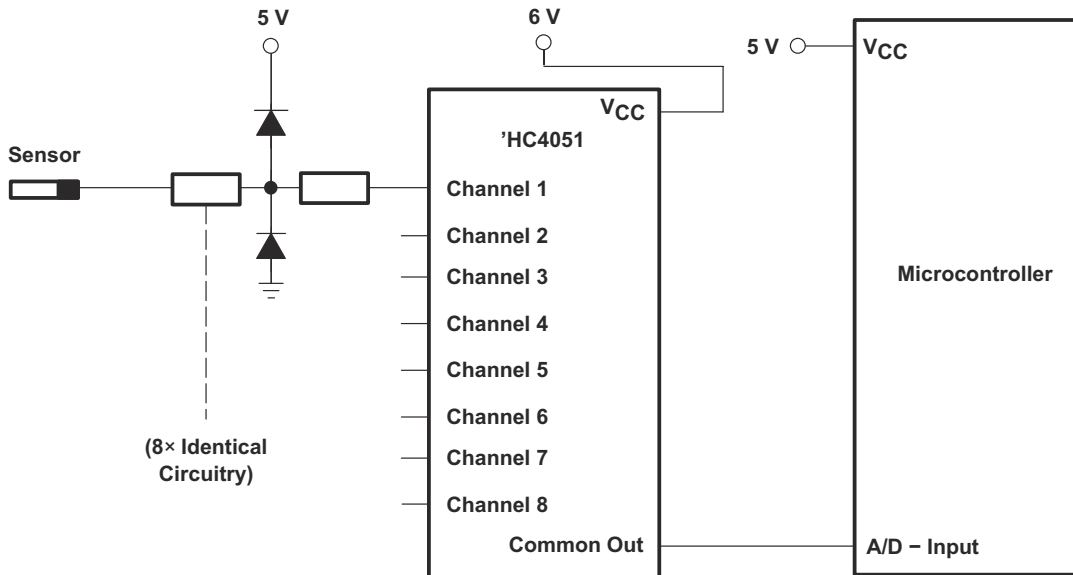


图 8-2. Alternate Solution Requires 32 Passive Components and One Extra 6-V Regulator to Suppress Injection Current Into a Standard ' HC4051 Multiplexer

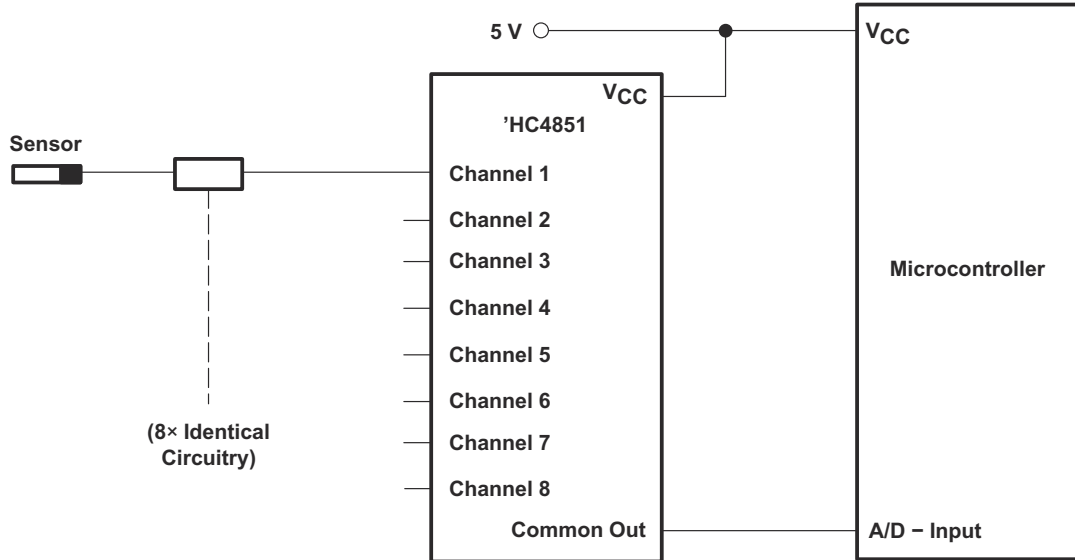


图 8-3. Solution by Applying the ' HC4851 Multiplexer

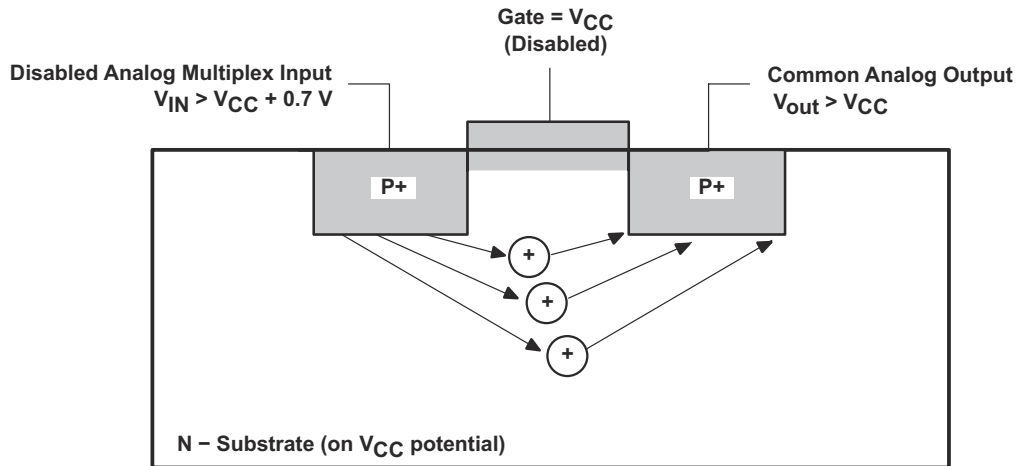


图 8-4. Diagram of Bipolar Coupling Mechanism (Appears if  $V_{IN}$  Exceeds  $V_{CC}$ , Driving Injection Current Into the Substrate)

## 9 Device and Documentation Support

TI offers an extensive line of development tools. Tools and software to evaluate the performance of the device, generate code, and develop solutions are listed below.

### 9.1 接收文档更新通知

要接收文档更新通知，请导航至 [ti.com](http://ti.com) 上的器件产品文件夹。点击 [通知](#) 进行注册，即可每周接收产品信息更改摘要。有关更改的详细信息，请查看任何已修订文档中包含的修订历史记录。

### 9.2 支持资源

TI E2E™ [中文支持论坛](#) 是工程师的重要参考资料，可直接从专家处获得快速、经过验证的解答和设计帮助。搜索现有解答或提出自己的问题，获得所需的快速设计帮助。

链接的内容由各个贡献者“按原样”提供。这些内容并不构成 TI 技术规范，并且不一定反映 TI 的观点；请参阅 TI 的 [使用条款](#)。

### 9.3 Trademarks

TI E2E™ is a trademark of Texas Instruments.  
所有商标均为其各自所有者的财产。

### 9.4 静电放电警告



静电放电 (ESD) 会损坏这个集成电路。德州仪器 (TI) 建议通过适当的预防措施处理所有集成电路。如果不遵守正确的处理和安装程序，可能会损坏集成电路。

ESD 的损坏小至导致微小的性能降级，大至整个器件故障。精密的集成电路可能更容易受到损坏，这是因为非常细微的参数更改都可能会导致器件与其发布的规格不相符。

### 9.5 术语表

[TI 术语表](#) 本术语表列出并解释了术语、首字母缩略词和定义。

## 10 Revision History

注：以前版本的页码可能与当前版本的页码不同

Changes from Revision B (January 2004) to Revision C (June 2024)	Page
• 通篇更新了表格、图和交叉参考的编号格式.....	1
• Changed VCC ABS Max from 7V to 6V.....	3
• Changed R <sup>θ</sup> JA.....	3
• Recommended supply changed from 6V to 5.5V and all test conditions using 6V were removed.....	4
• Changed ttran, tON, tOFF parameters.....	6
• Added Mechanical, Packaging, and Orderable Information section.....	12

## 11 Mechanical, Packaging, and Orderable Information

The following pages include mechanical packaging and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser based versions of this data sheet, refer to the left hand navigation.

**PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SN74HC4851D	NRND	SOIC	D	16	40	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	HC4851	
SN74HC4851DGVR	NRND	TVSOP	DGV	16	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	HC4851	
SN74HC4851DR	NRND	SOIC	D	16	2500	RoHS & Green	NIPDAU   SN	Level-1-260C-UNLIM	-40 to 125	HC4851	
SN74HC4851DRG4	NRND	SOIC	D	16	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	HC4851	
SN74HC4851N	NRND	PDIP	N	16	25	RoHS & Green	NIPDAU	N / A for Pkg Type	-40 to 125	SN74HC4851N	
SN74HC4851PW	ACTIVE	TSSOP	PW	16	90	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	HC4851	Samples
SN74HC4851PWR	ACTIVE	TSSOP	PW	16	2000	RoHS & Green	NIPDAU   SN	Level-1-260C-UNLIM	-40 to 125	HC4851	Samples
SN74HC4851PWRG4	ACTIVE	TSSOP	PW	16	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	HC4851	Samples

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSELETE:** TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

**RoHS Exempt:** TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

**Green:** TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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**OTHER QUALIFIED VERSIONS OF SN74HC4851 :**

- Automotive : [SN74HC4851-Q1](#)

NOTE: Qualified Version Definitions:

- Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects

**TAPE AND REEL INFORMATION**

**QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74HC4851DGVR	TVSOP	DGV	16	2000	330.0	12.4	6.8	4.0	1.6	8.0	12.0	Q1
SN74HC4851DR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
SN74HC4851DRG4	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
SN74HC4851PWR	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
SN74HC4851PWRG4	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1

**TAPE AND REEL BOX DIMENSIONS**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74HC4851DGVR	TVSOP	DGV	16	2000	356.0	356.0	35.0
SN74HC4851DR	SOIC	D	16	2500	340.5	336.1	32.0
SN74HC4851DRG4	SOIC	D	16	2500	340.5	336.1	32.0
SN74HC4851PWR	TSSOP	PW	16	2000	356.0	356.0	35.0
SN74HC4851PWRG4	TSSOP	PW	16	2000	356.0	356.0	35.0



**TUBE**


\*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (μm)	B (mm)
SN74HC4851D	D	SOIC	16	40	507	8	3940	4.32
SN74HC4851N	N	PDIP	16	25	506	13.97	11230	4.32
SN74HC4851PW	PW	TSSOP	16	90	530	10.2	3600	3.5

DGV (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE

24 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.  
 B. This drawing is subject to change without notice.  
 C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.  
 D. Falls within JEDEC: 24/48 Pins – MO-153  
 14/16/20/56 Pins – MO-194

N (R-PDIP-T\*\*)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
  - The 20 pin end lead shoulder width is a vendor option, either half or full width.

D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
  - D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
  - E. Reference JEDEC MS-012 variation AC.

D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



4211283-4/E 08/12

- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Publication IPC-7351 is recommended for alternate designs.
  - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
  - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-153.

# EXAMPLE BOARD LAYOUT

PW0016A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE  
EXPOSED METAL SHOWN  
SCALE: 10X



SOLDER MASK DETAILS

4220204/A 02/2017

NOTES: (continued)

- 6. Publication IPC-7351 may have alternate designs.
- 7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

# EXAMPLE STENCIL DESIGN

PW0016A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE  
BASED ON 0.125 mm THICK STENCIL  
SCALE: 10X

4220204/A 02/2017

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.



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